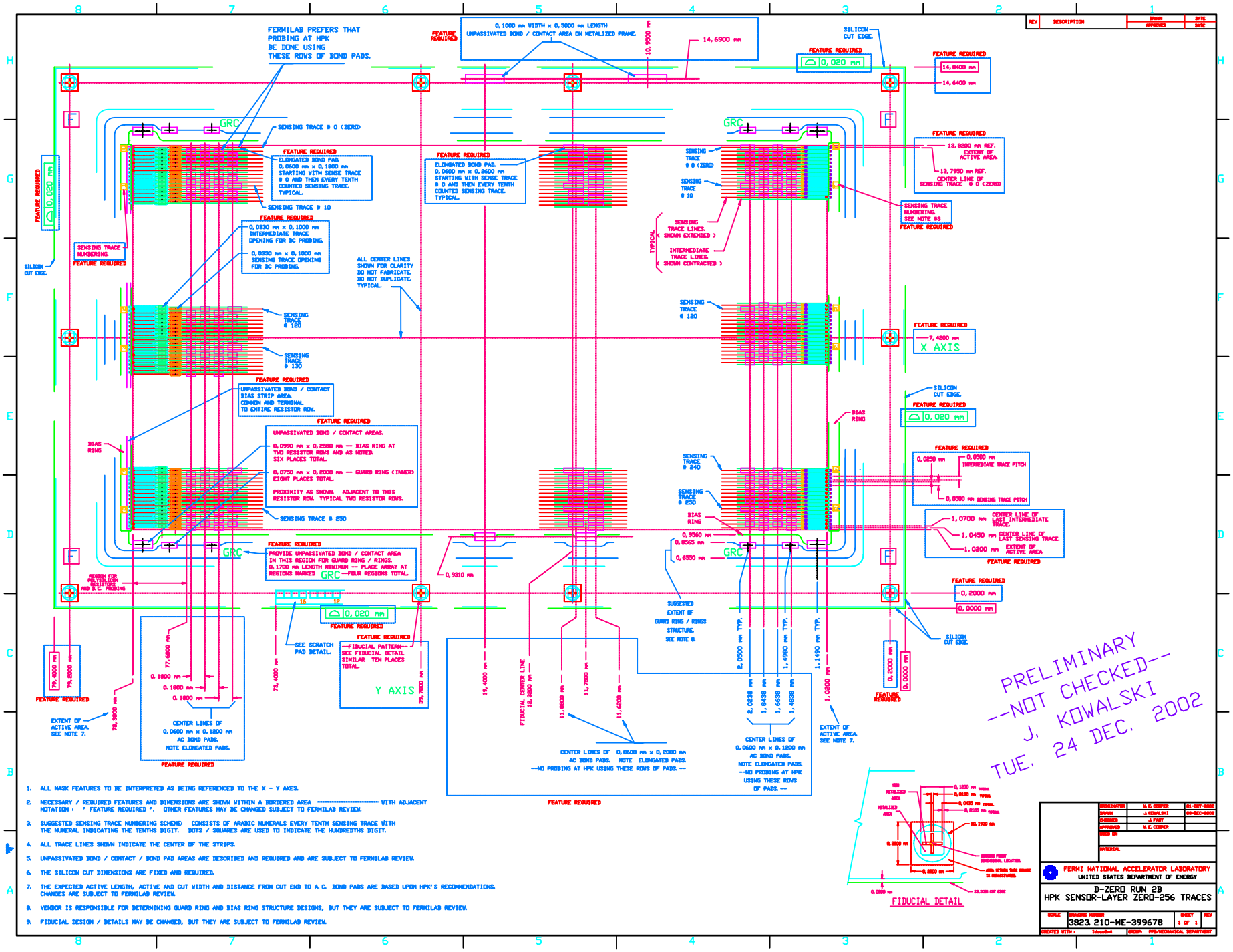

1. ALL MASK FEATURES TO BE INTERPRETED AS BEING REFERENCED TO THE X - Y AXES.
2. NECESSARY / REQUIRED FEATURES AND DIMENSIONS ARE SHOWN WITHIN A BORDERED AREA ———————— WITH ADJACENT NOTATION : " FEATURE REQUIRED ". OTHER FEATURES MAY BE CHANGED SUBJECT TO FERMILAB REVIEW.
3. SUGGESTED SENSING TRACE NUMBERING SCHEME: CONSISTS OF ARABIC NUMERALS EVERY TENTH SENSING TRACE WITH THE NUMERAL INDICATING THE TENTHS DIGIT. DOTS / SQUARES ARE USED TO INDICATE THE HUNDREDTHS DIGIT.
4. ALL TRACE LINES SHOWN INDICATE THE CENTER OF THE STRIPS.
5. UNPASSIVATED BOND / CONTACT / BOND PAD AREAS ARE DESCRIBED AND REQUIRED AND ARE SUBJECT TO FERMILAB REVIEW.
6. THE SILICON CUT DIMENSIONS ARE FIXED AND REQUIRED.
7. THE EXPECTED ACTIVE LENGTH, ACTIVE AND CUT WIDTH AND DISTANCE FROM CUT END TO A.C. BOND PADS ARE BASED UPON HPK'S RECOMMENDATIONS. CHANGES ARE SUBJECT TO FERMILAB REVIEW.
8. VENDOR IS RESPONSIBLE FOR DETERMINING GUARD RING AND BIAS RING STRUCTURE DESIGNS, BUT THEY ARE SUBJECT TO FERMILAB REVIEW.
9. FIDUCIAL DESIGN / DETAILS MAY BE CHANGED, BUT THEY ARE SUBJECT TO FERMILAB REVIEW.